



Material Content Data Sheet



Sales Product Name		IPG20N06S2L-35		Issued		23. January 2018			
MA#		MA001668852							
Package		PG-TDSON-8-4		Weight*		97.53 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.173	3.25	3.25	32537	32537	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		138		
	non noble metal	iron	7439-89-6	0.045	0.05		458		
	non noble metal	copper	7440-50-8	44.654	45.79	45.85	457854	458450	
	non noble metal	aluminium	7429-90-5	0.762	0.78	0.78	7811	7811	
wire	non noble metal	aluminium	7429-90-5	0.762	0.78	0.78	7811	7811	
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		903		
	plastics	epoxy resin	-	6.255	6.41		64133		
	inorganic material	silicondioxide	60676-86-0	37.705	38.66	45.16	386603	451639	
leadfinish	non noble metal	tin	7440-31-5	1.308	1.34	1.34	13408	13408	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	492	493	
solder	non noble metal	tin	7440-31-5	0.070	0.07		713		
	noble metal	silver	7440-22-4	0.087	0.09		892		
	non noble metal	lead	7439-92-1	3.322	3.41	3.57	34057	35662	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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